

Electronic Patent Application Fee Transmittal

Application Number:	10648586			
Filing Date:	26-Aug-2003			
Title of Invention:	Wafer-level chip scale package			
First Named Inventor/Applicant Name:	Efren M. Lacap			
Filer:	Philip Van Uytendaele Dizerega/Chalynda Renz			
Attorney Docket Number:	408204			
Filed as Small Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	2401	1	250	250
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				250